Integrated Electrochemical Treatment of **CMP** Waste Streams for Water Reclaim and **Conservation** (Customized Project)

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Water Resources Research Center

Objectives

- Develop methods for removing Cu²⁺ (electrochemically), H₂O₂ (catalytically), and other contaminants from wastewater generated during CMP.
- Build a prototype reactor and pilot test on real CMP wastewater.
- Estimate total costs of ownership for reclaiming CMP wastewater.

ESH Metrics and Impact

- 1. Reduction in emission of ESH-problematic material to the environment
- Eliminate the disposal problems associated with membrane concentrates.
- Eliminate the disposal of Cu-laden nanoparticles into hazardous waste landfills.
- 2. Reduction in the use of natural resources (water and energy)
- Reclaim CMP wastewater for reuse.
- CMP wastewater accounts for up to 30% of fab water use.
- 3. Reduction in the use of chemicals
- Eliminate the need for pH adjusting chemicals and reducing agents that add to TDS load.
- Eliminate the need for activated carbon regeneration.

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Opportunity statement

Natural Resources: Water Conservation

- CMP accounts for ~30% of water use in the fab
- CMP waste water is generated at 25-40m³/day/tool or 500-750m³/day for a 20-tool fleet (0.15 to 0.2 MGD)
- CMP waste waters are not broadly reclaimed at present w/in Intel
- Use of reclaimed CMP waste in industrial waters could, for example, easily supply 0.1 MDG for use in cooling towers, or provide feedstock for URW system

• Bulk Chemicals: Reduction of Acid/Base Use

 pH adjustments are done electrochemically and economically ⇒ no need to purchase, ship and store acids and bases to implement the technology

• Equipment and Process: Green Alternative

 electrochemical methods avoid addition of salt (e.g. Cl⁻ and SO₄²⁻) and generation of brine streams ⇒ better salinity management in areas such as the Desert SW United States

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Current Research and Differentiators

CMP waste characteristics

- 5 20 ppm of dissolved copper
- 500 1000 ppm of total suspended solids (TSS);
 50 to 600nm particles of silica, alumina, ceria and/or polishing pad
- 100 400 ppm of total dissolved solids (TDS)
- organic complexants (*e.g.*, citric acid)
- organic corrosion inhibitors (*e.g.*, benzotriazole)
- oxidizing agents (*e.g.*, H₂O₂)

Standard separate treatment steps⁺

- 1. oxidizer removal
- 2. organics removal
- 3. TSS reduction
- 4. trace metal removal

[†]no order implied

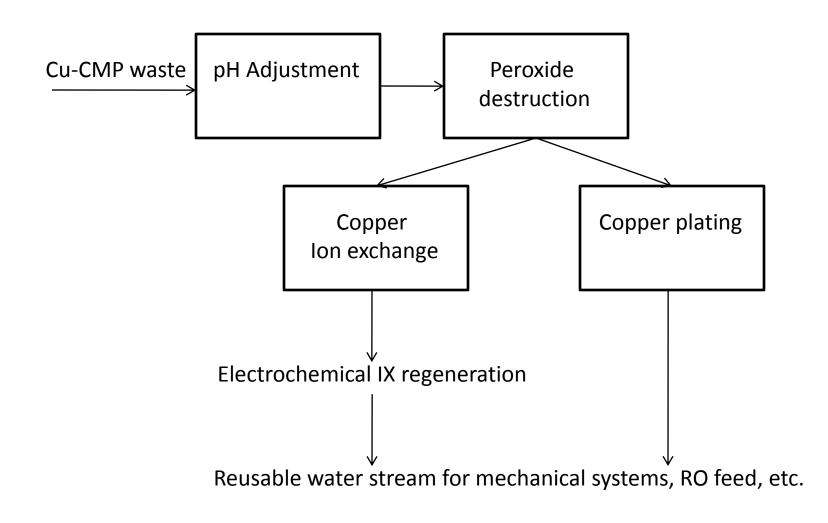
Present treatment methods include:

- 1. Chemical pH adjustment
- 2. Addition of reducing agents
- 3. Solid/liquid separation (MF, UF, RO)
- 4. Ion exchange

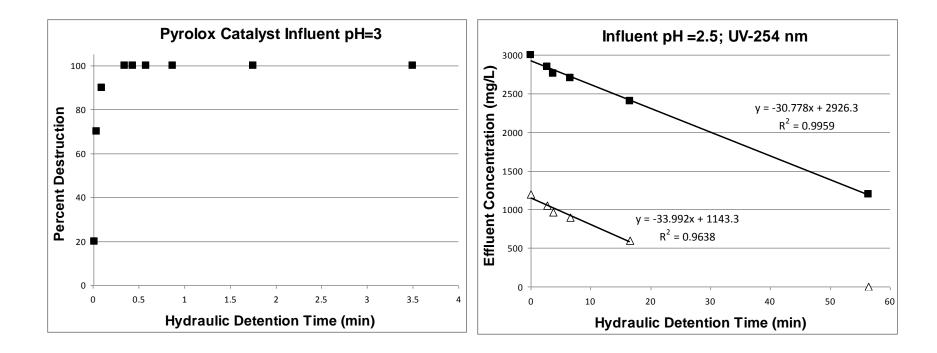
Drawbacks to current methods include:

- pH adjusting chemicals increase TDS (e.g., Cl⁻ or Na⁺)
- 2. The need for addition chemical reducing agents to remove H_2O_2 that increase TDS
- 3. The generation of brine solutions from ionexchange regeneration
- 4. The generation of concentrates from solid/liquid separations

Proposed Approach

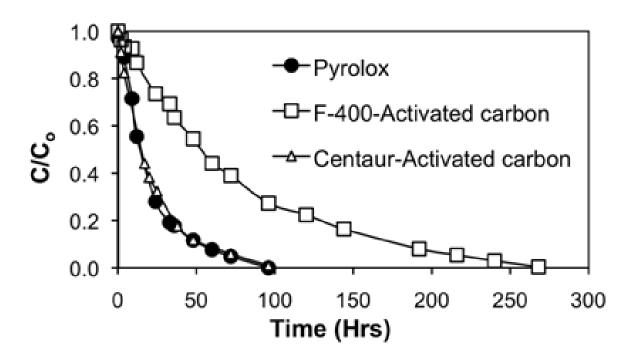


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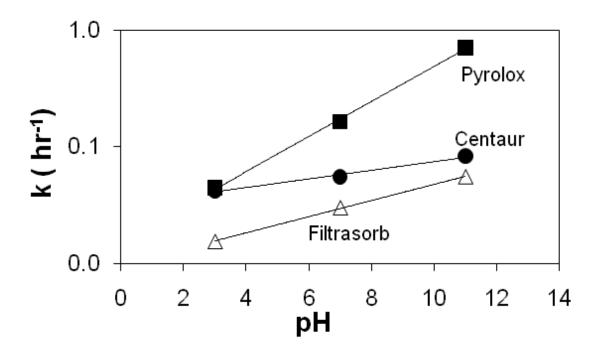
- Conducted tests on six possible peroxide destruction catalysts.
- Conducted tests on ultrasonic and UV-light peroxide destruction.
- Pyrolox® (pyrolusite-MnO₂) catalyst determined to be the most effective.
- H₂O₂ destruction rates with both 185 and 354 nm UV light were too slow for practical implementations.

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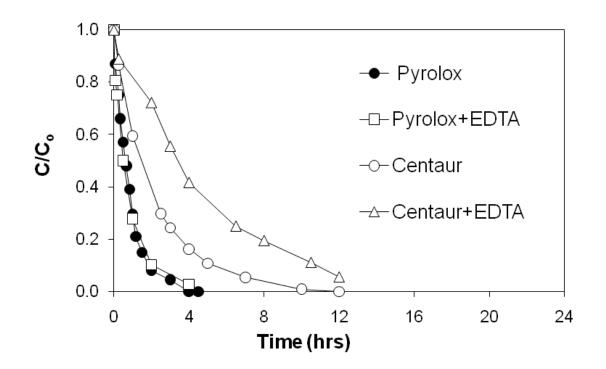
- Pyrolox catalyst compared to activated carbon catalysts (Filtrasorb® and Centaur®)
 - pH 3, in the absence of chelating compounds
- Activated carbon and pyrolox can perform identically under these conditions

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Pyrolox excels as a peroxide destruction catalyst at neutral and high pH values

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Pyrolox maintains its effectiveness in the presence of chelating compounds.

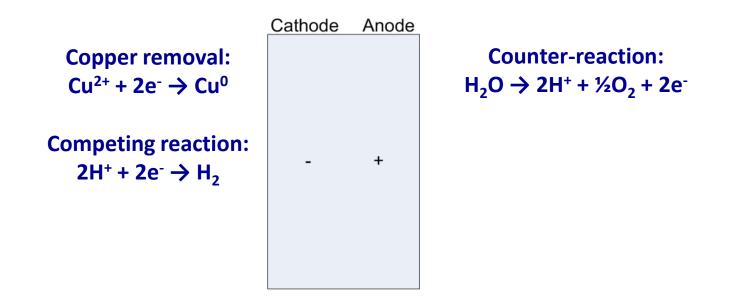
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Electrochemistry Background

- Why electrochemistry?
 - elimination of chemical additives
 - elimination of secondary waste stream production requiring further treatment or disposal (*e.g.*, ion exchange brines)
 - small footprint, low capital and operating costs

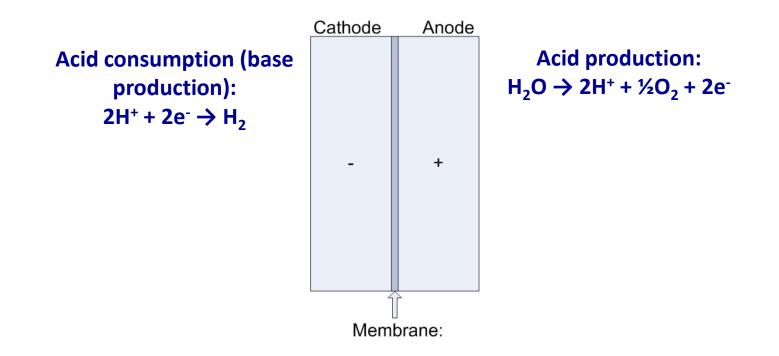
Electrochemistry Background

Copper plating: net result of the process is copper removal from the liquid and a lower pH.

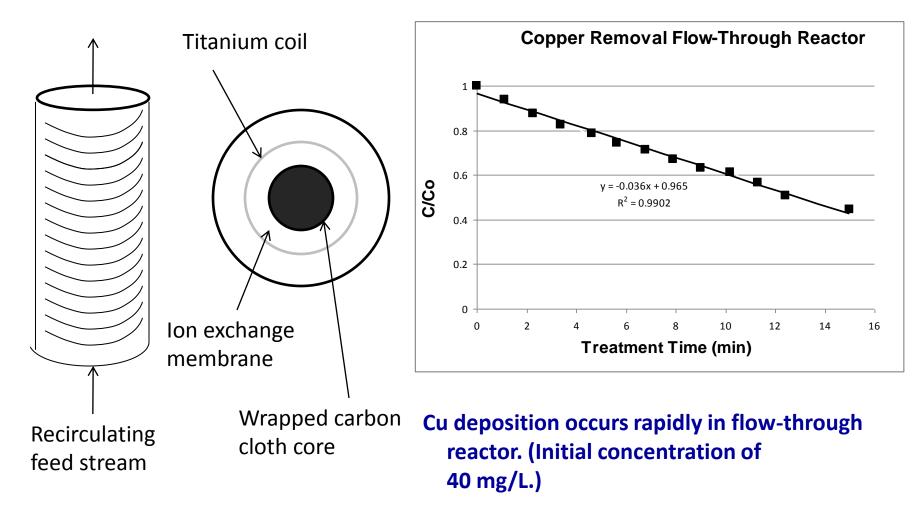


Electrochemistry Background

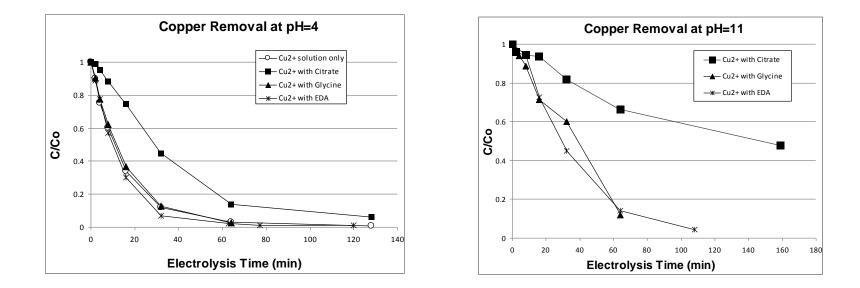
Electrochemical pH adjustment: pH is increased on one side of the membrane and lowered on the other side



Electrodeposition of Cu²⁺ in Flow-through Reactor



Electrodeposition of Cu on Carbon Cloth Cathode



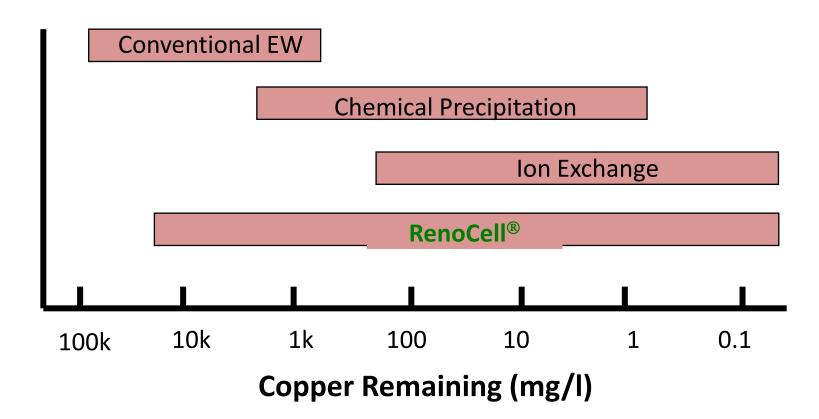
- Investigated the effect of chelating agents on electrodeposition of Cu in batch reactors in solutions with low and high pH values.
- Ethylenediamine (EDA) and glycine do not affect Cu deposition rates.
- Cu deposition occurs at both low and high solution pH values.

Commercial Scale Reactors



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Effective Operating Ranges for Metal Removal Technologies

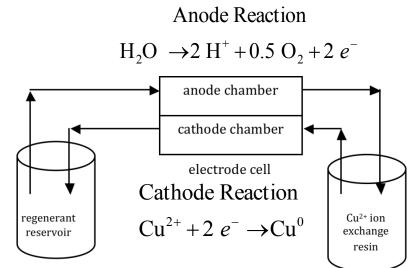


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Experimental System

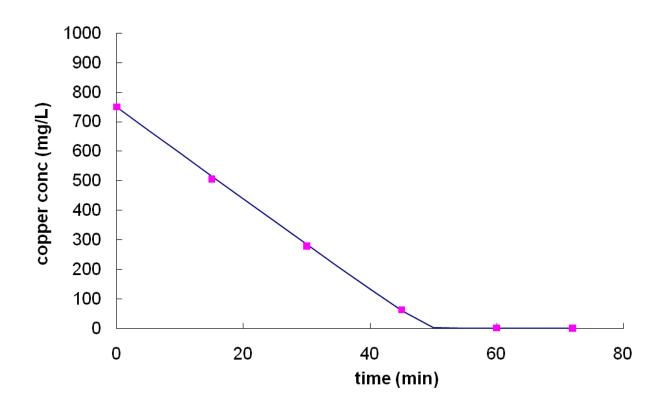
- Copper plating system:
 - Renovare M100 RenoCell (bench scale test system)
- S-930 Purolite cation exchange resin
 - Chelating, iminodiacetic functional groups







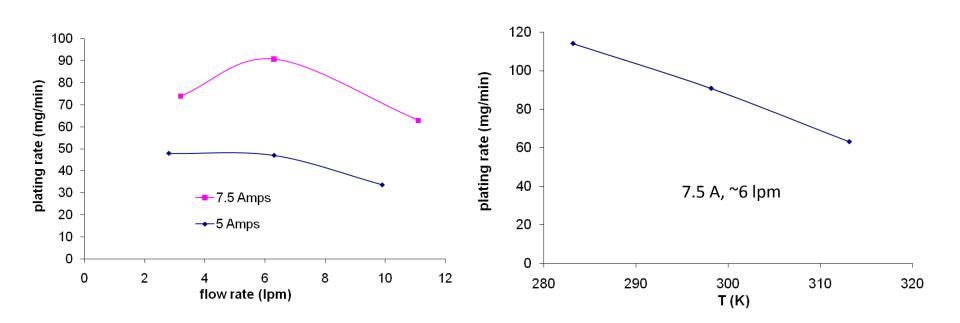
Copper Plating Only



Copper plates at a constant rate at high concentrations, and follows a first-order rate law at low concentrations.

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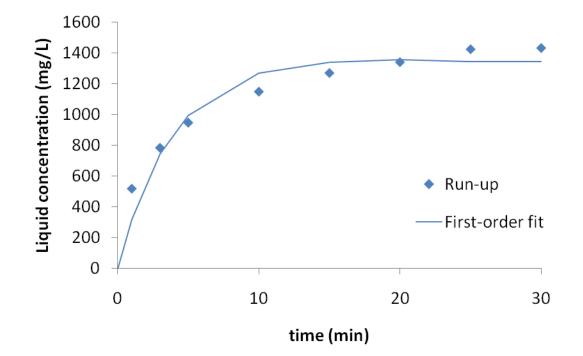
Copper Plating Only



Copper plating rate depends on temperature, flow rate, current

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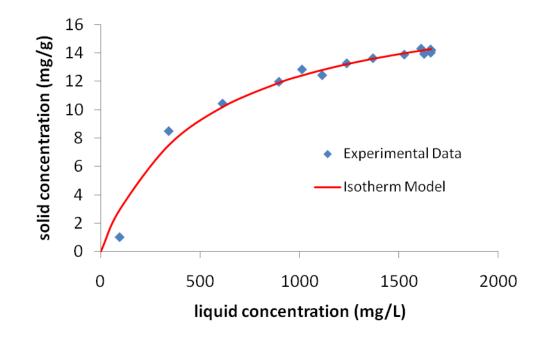
Ion Exchange Resin Regeneration Only



Copper removal from the ion exchange resin can be approximated using first-order models, although knowledge of the isotherm can improve the description of the process.

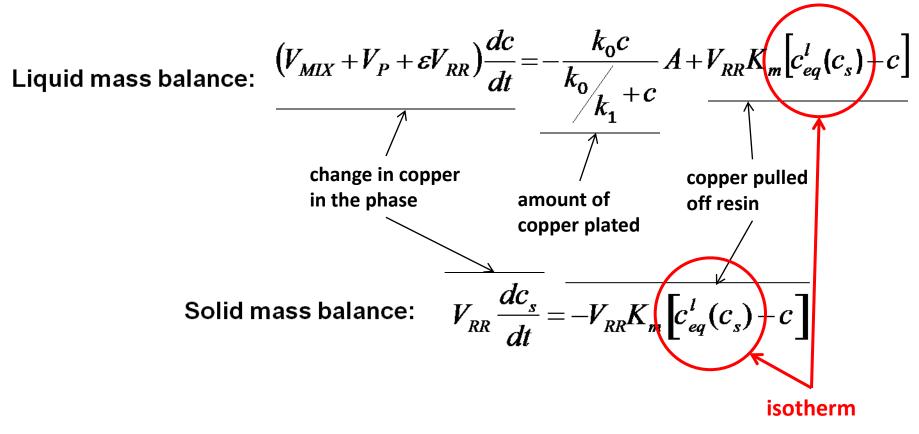
Finding the Isotherm

Copper removal from the resin happens quickly compared to copper plating → the liquid concentration stays close to equilibrium with the resin

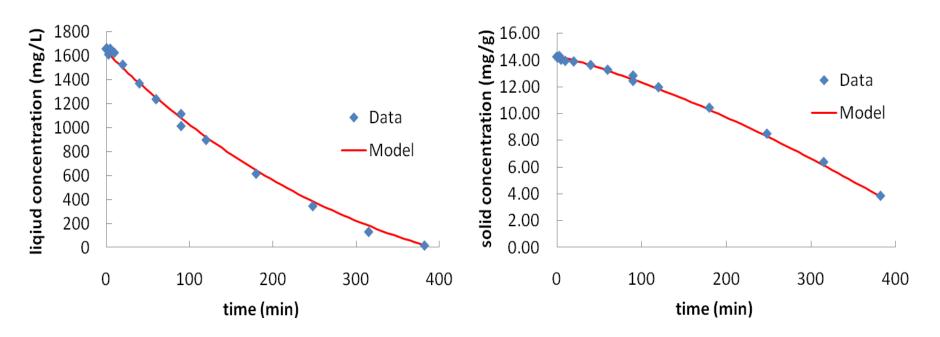


Combined Resin Regeneration Process

Process model:



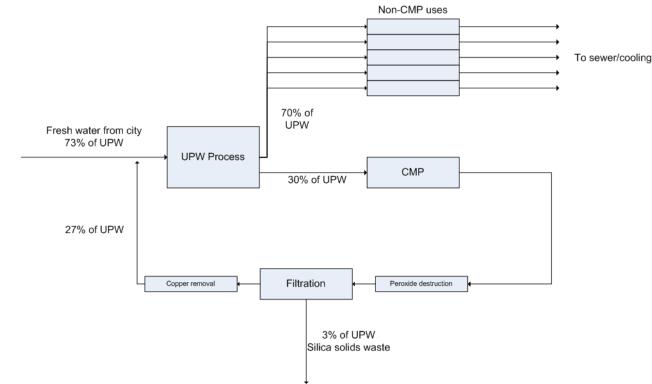
Combined Resin Regeneration Process



- Modeling can predict both liquid and solid phase Cu²⁺ concentrations
- Modeling will be used to scale-up from prototype to full scale system

Parameters: $V_{MIX} = 6.0$ L; $V_{RR} = 3.4$ L; $V_P = 3.0$ L; $\varepsilon = 0.3$; $K_m = 0.162$ min⁻¹ Isotherm: $c_{liq} = (1/(1.97 \times 10^{-3})) \times (c_{sol}/(18.6 - c_{sol}))$, c_{liq} in mg/L, c_{sol} in mg/g

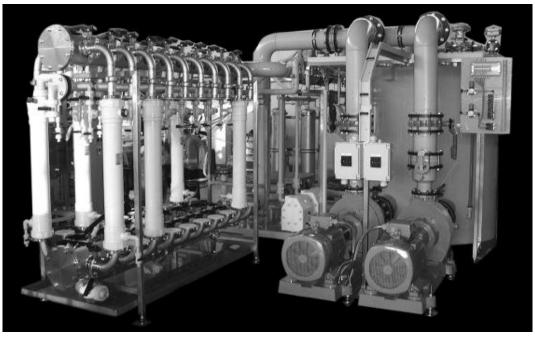
Proposed Treatment System (e.g.)



- 1. Peroxide is oxidized using Pyrolox catalyst
- 2. Copper is removed via ion exchange, the resin for which can be regenerated
- 3. Result is a clean water stream and concentrated solid slurry

Proposed Treatment System

- Biggest economic concern is the filtration
 - Pall Corp. filters -\$1.80-\$3.20/1000 gallons



- Other costs:
 - Electricity for plating
 - Initial investments for pyrolox and ion exchange media

Proposed Treatment System

- Economic benefits:
 - Recovery of copper
 Power cost = \$8.40/m³-resin
 Cu value = \$240/m³-resin
 - Recovery of water stream avoids costs for municipal sewer and fresh water
 - e.g. Rio Rancho, NM, sewer costs are \$6.30/1000 gal and water costs are \$3.24/1000 gal
 - After filtration, at least \$6.34/1000 gal for other treatment
 - At 300,000 gallons/day, this is about \$700,000/year for recovery of capital costs or as savings
- Environmental benefits:
 - Reduced water "footprint"
 - Potential contaminants are kept out of sewer system

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Conclusions

- Hydrogen peroxide and copper can be effectively removed from CMP wastes using catalytic and electrochemical methods.
- Regeneration of ion exchange resins can be effectively modeled to predict system performance.
- Water reuse can be accomplished in economically feasible systems, with costs comparable to municipal treatment fees.

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